

Product Summary

| $V_{(BR)DSS}$ | $R_{DS(on) \text{ max}}$ | I_D $T_A = 25^\circ\text{C}$ |
|---------------|---------------------------------------|-----------------------------------|
| 60V | 40m Ω @ $V_{GS} = 10\text{V}$ | 5.0A |
| | 55m Ω @ $V_{GS} = 4.5\text{V}$ | 4.4A |

Features and Benefits

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

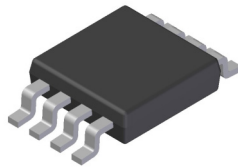
Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

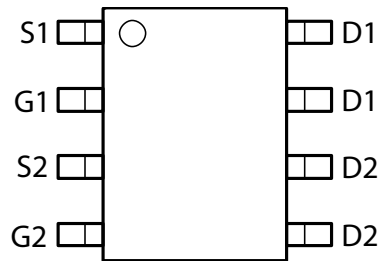
- DC-DC Converters
- Power management functions
- Backlighting

Mechanical Data

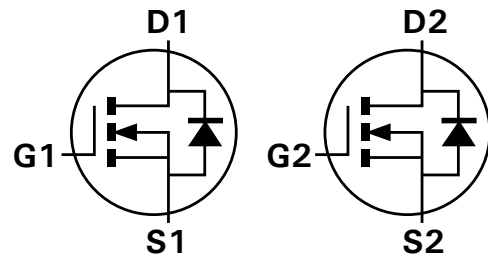
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)



Top View



Top View
Pin Configuration



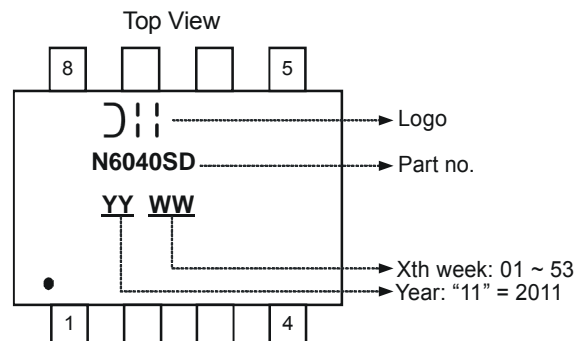
Equivalent Circuit

Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|------|-------------------|
| DMN6040SSD-13 | SO-8 | 2,500/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | | | Symbol | Value | Units |
|--|------------------|--|-----------|------------|-------|
| Drain-Source Voltage | | | V_{DSS} | 60 | V |
| Gate-Source Voltage | | | V_{GSS} | ± 20 | V |
| Continuous Drain Current (Note 6) $V_{GS} = 10\text{V}$ | Steady State | $T_A = 25^\circ\text{C}$ $T_A = 70^\circ\text{C}$ | I_D | 5.0 4.1 | A |
| | $t < 10\text{s}$ | $T_A = 25^\circ\text{C}$ $T_A = 70^\circ\text{C}$ | I_D | 6.6 5.3 | A |
| Maximum Body Diode Forward Current (Note 6) | | | I_S | 2.5 | A |
| Pulsed Drain Current (10 μs pulse, duty cycle = 1%) | | | I_{DM} | 30 | A |
| Avalanche Current (Note 7) $L = 0.1\text{mH}$ | | | I_{AS} | 14.2 | A |
| Avalanche Energy (Note 7) $L = 0.1\text{mH}$ | | | E_{AS} | 10 | mJ |

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | | Symbol | Value | Units |
|--|--------------------------|-----------------|-------------|--------------------|
| Total Power Dissipation (Note 5) | $T_A = 25^\circ\text{C}$ | P_D | 1.3 | W |
| | $T_A = 70^\circ\text{C}$ | | 0.8 | |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady state | $R_{\theta JA}$ | 102 | $^\circ\text{C/W}$ |
| | $t < 10\text{s}$ | | 61 | |
| Total Power Dissipation (Note 6) | $T_A = 25^\circ\text{C}$ | P_D | 1.7 | W |
| | $T_A = 70^\circ\text{C}$ | | 1.1 | |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady state | $R_{\theta JA}$ | 75 | $^\circ\text{C/W}$ |
| | $t < 10\text{s}$ | | 50 | |
| Thermal Resistance, Junction to Case (Note 6) | | $R_{\theta JC}$ | 14.5 | |
| Operating and Storage Temperature Range | | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ |

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|--------------|-----|------|-----------|------------|---|
| OFF CHARACTERISTICS (Note 8) | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | 60 | — | — | V | $V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$ |
| Zero Gate Voltage Drain Current | I_{DSS} | — | — | 100 | nA | $V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$ |
| Gate-Source Leakage | I_{GSS} | — | — | ± 100 | nA | $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$ |
| ON CHARACTERISTICS (Note 8) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | 1 | — | 3 | V | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$ |
| Static Drain-Source On-Resistance | $R_{DS(on)}$ | — | 30 | 40 | m Ω | $V_{GS} = 10\text{V}, I_D = 4.5\text{A}$ |
| | | — | 35 | 55 | | $V_{GS} = 4.5\text{V}, I_D = 3.5\text{A}$ |
| Forward Transfer Admittance | $ Y_{fs} $ | — | 4.5 | — | S | $V_{DS} = 10\text{V}, I_D = 4.3\text{A}$ |
| Diode Forward Voltage | V_{SD} | — | 0.7 | 1.2 | V | $V_{GS} = 0\text{V}, I_S = 1\text{A}$ |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | |
| Input Capacitance | C_{iss} | — | 1287 | — | pF | $V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$ |
| Output Capacitance | C_{oss} | — | 57 | — | | |
| Reverse Transfer Capacitance | C_{rss} | — | 44 | — | | |
| Gate Resistance | R_G | — | 1.2 | — | Ω | $V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$ |
| Total Gate Charge ($V_{GS} = 10\text{V}$) | Q_g | — | 22.4 | — | nC | $V_{DS} = 30\text{V}, I_D = 4.3\text{A}$ |
| Total Gate Charge ($V_{GS} = 4.5\text{V}$) | $Q_{g4.5}$ | — | 10.4 | — | | |
| Gate-Source Charge | Q_{gs} | — | 4.9 | — | | |
| Gate-Drain Charge | Q_{gd} | — | 3.0 | — | | |
| Turn-On Delay Time | $t_{D(on)}$ | — | 6.6 | — | nS | $V_{GS} = 10\text{V}, V_{DD} = 30\text{V}, R_G = 6\Omega,$ $I_D = 4.3\text{A}$ |
| Turn-On Rise Time | t_r | — | 8.1 | — | | |
| Turn-Off Delay Time | $t_{D(off)}$ | — | 20.1 | — | | |
| Turn-Off Fall Time | t_f | — | 4.0 | — | | |
| Body Diode Reverse Recovery Time | t_{rr} | — | 18 | — | nS | $I_S = 4.3\text{A}, dI/dt = 100\text{A}/\mu\text{s}$ |
| Body Diode Reverse Recovery Charge | Q_{rr} | — | 11.9 | — | nC | $I_S = 4.3\text{A}, dI/dt = 100\text{A}/\mu\text{s}$ |

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 - I_{AR} and E_{AR} rating are based on low frequency and duty cycles to keep $T_J = 25^\circ\text{C}$
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

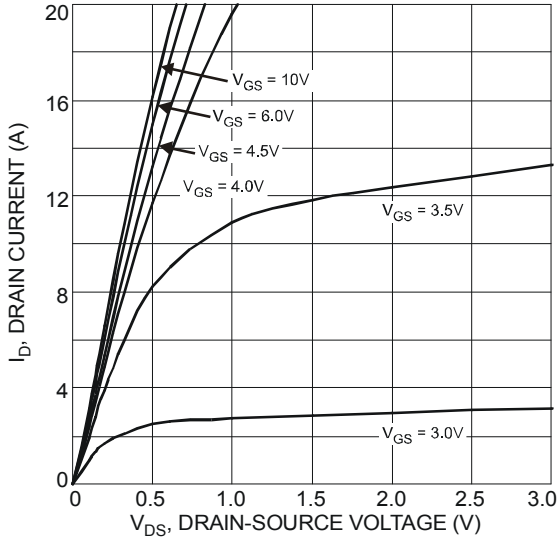


Fig. 1 Typical Output Characteristic

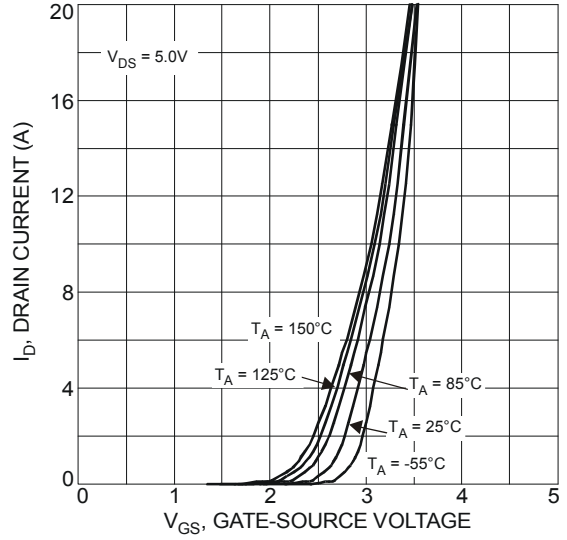


Fig. 2 Typical Transfer Characteristics

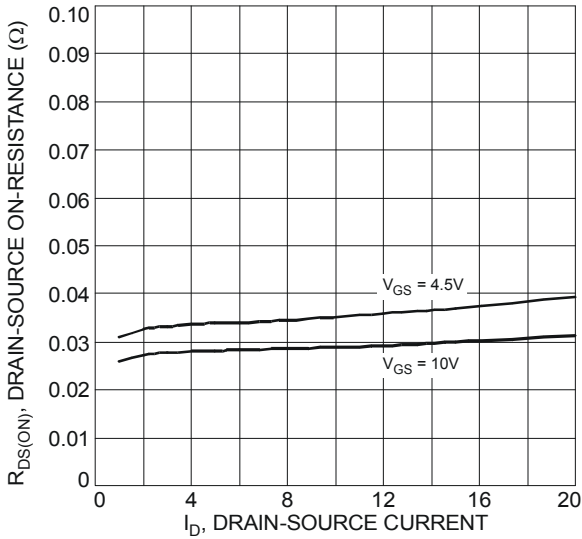


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

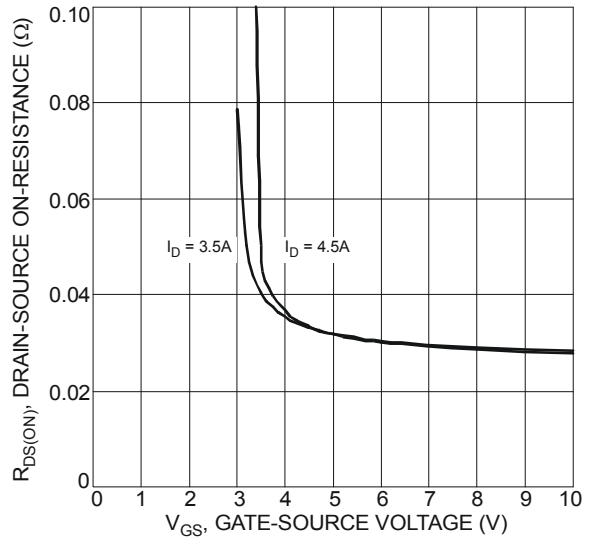


Fig. 4 Typical On-Resistance vs. Drain Current and Gate Voltage

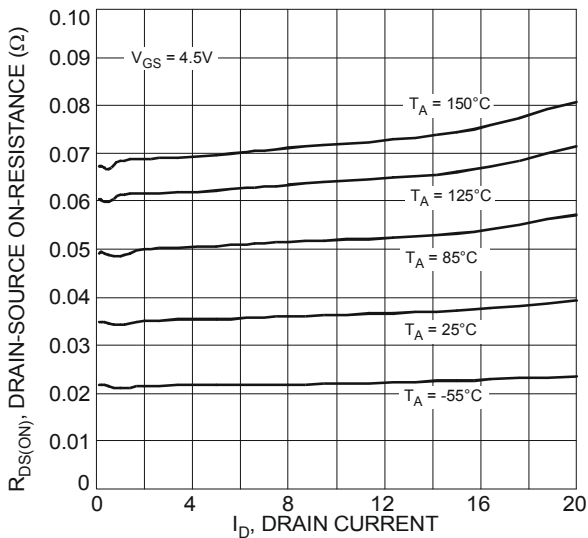


Fig. 5 Typical On-Resistance vs. Drain Current and Temperature

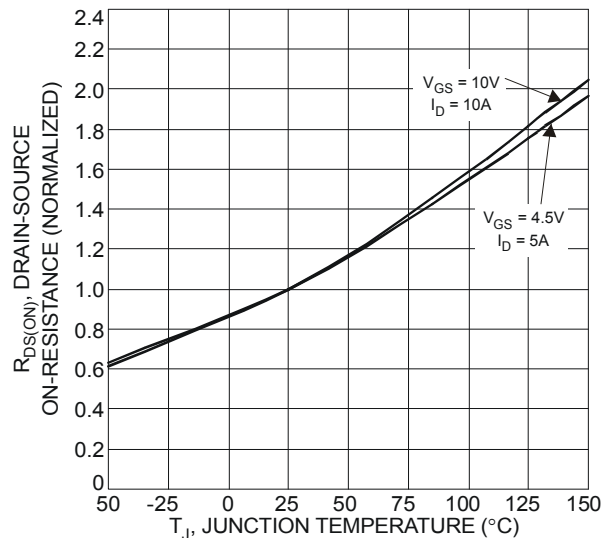


Fig. 6 On-Resistance Variation with Temperature

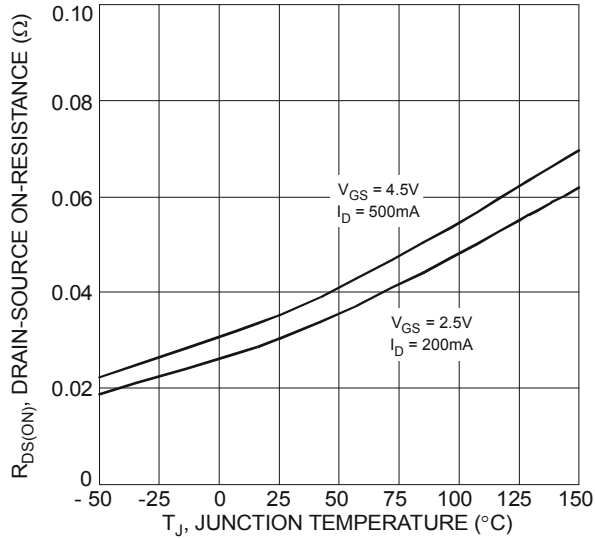


Fig. 7 On-Resistance Variation with Temperature

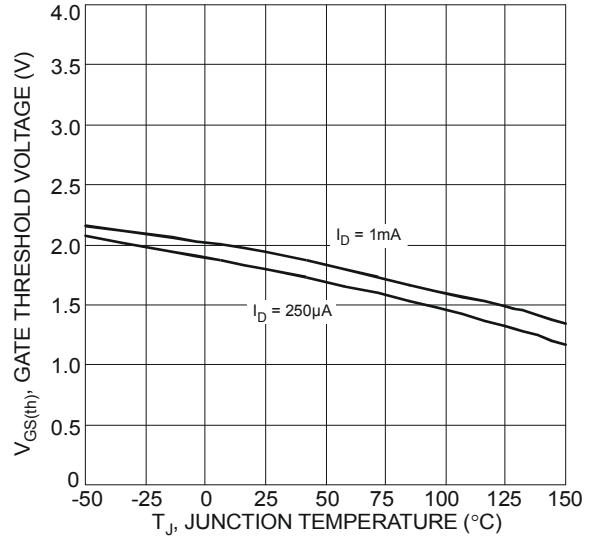


Fig. 8 Gate Threshold Variation vs. Ambient Temperature

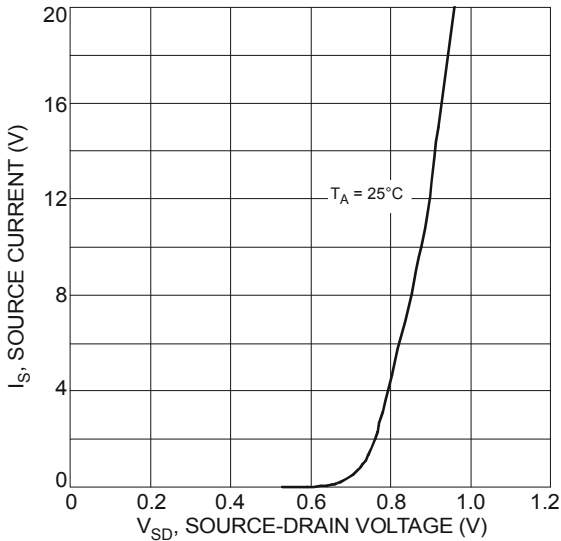


Fig.9 Diode Forward Voltage vs. Current

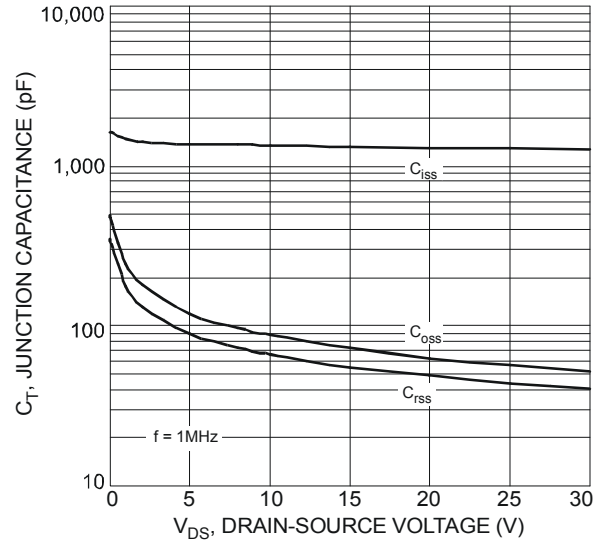


Fig. 10 Typical Junction Capacitance

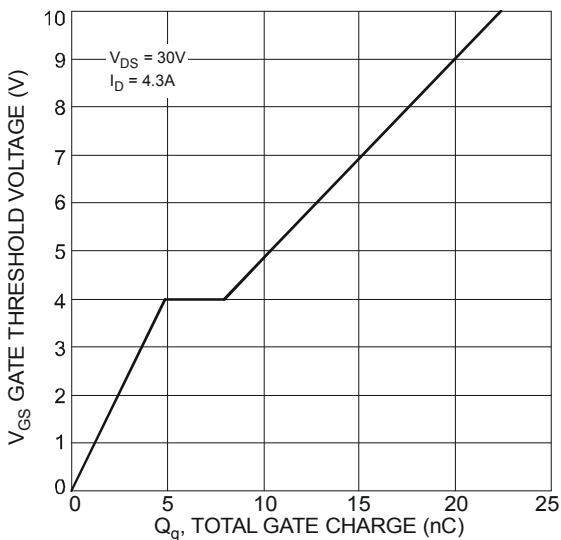
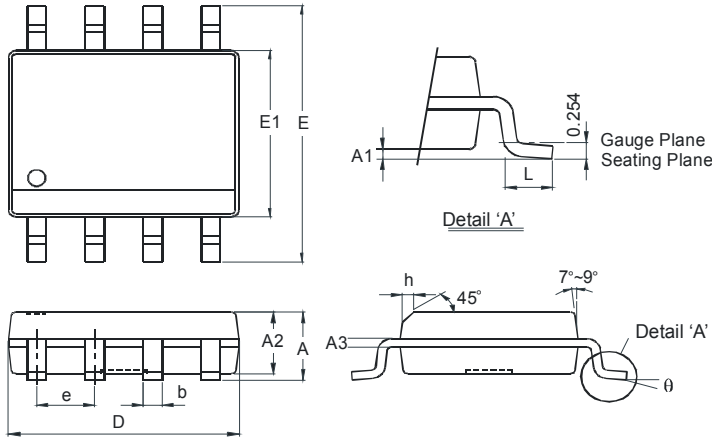


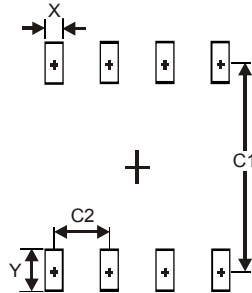
Fig. 11 Gate Charge

Package Outline Dimensions



| SO-8 | | |
|----------------------|----------|------|
| Dim | Min | Max |
| A | - | 1.75 |
| A1 | 0.10 | 0.20 |
| A2 | 1.30 | 1.50 |
| A3 | 0.15 | 0.25 |
| b | 0.3 | 0.5 |
| D | 4.85 | 4.95 |
| E | 5.90 | 6.10 |
| E1 | 3.85 | 3.95 |
| e | 1.27 Typ | |
| h | - | 0.35 |
| L | 0.62 | 0.82 |
| θ | 0° | 8° |
| All Dimensions in mm | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| X | 0.60 |
| Y | 1.55 |
| C1 | 5.4 |
| C2 | 1.27 |

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